



Material Content Data Sheet



Sales Product Name	SAF-XC824M-1FGI AA			Issued		29. August 2013		
MA#	MA000841878							
Package	PG-DSO-20-45			Weight*		587.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.299	0.73	0.73	7315	7315
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		81	
	non noble metal	zinc	7440-66-6	0.190	0.03		323	
	non noble metal	iron	7439-89-6	3.797	0.65		6460	
	non noble metal	copper	7440-50-8	154.185	26.23	26.92	262316	269180
wire	noble metal	gold	7440-57-5	0.651	0.11	0.11	1107	1107
encapsulation	organic material	carbon black	1333-86-4	0.835	0.14		1420	
	plastics	epoxy resin	-	38.401	6.53		65333	
	inorganic material	silicondioxide	60676-86-0	378.170	64.34	71.01	643383	710136
leadfinish	non noble metal	tin	7440-31-5	4.487	0.76	0.76	7633	7633
plating	noble metal	silver	7440-22-4	0.800	0.14	0.14	1361	1361
glue	plastics	epoxy resin	-	0.480	0.08		817	
	noble metal	silver	7440-22-4	1.441	0.25	0.33	2451	3268
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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